



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N:
- CL05A105KQ5NNND

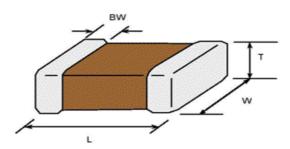
(Reference sheet)

- Description :
- CAP, 1uF, 6.3V, ±10%, X5R, 0402

A. Samsung Part Number

		<u>CL</u> ①	<u>05</u> ②	<u>А</u> З	<u>105</u> ④	<u>K</u> 5	<mark>Q</mark> 6	<u>5</u> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>▶</u> ∭
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0402 (inch o	code)		L: 1	1.00	± 0.05	mm			W:	0.50 ± 0.05 mm
3	Dielectric	X5R				8	Inner	elect	rode			Ni
4	Capacitance	1 uF					Term	inatic	on			Cu
5	Capacitance	±10 %					Platin	g				Sn 100% (Pb Free)
	tolerance					9	Produ	uct				Normal
6	Rated Voltage	6.3 V				10	Speci	al				Reserved for future use
\overline{O}	Thickness	0.50 ± 0.05 mm				1	Packa	aging	I			Cardboard Type, 13" reel

B. Structure & Dimension



Samsung P/N	Dimension(mm)							
Samsung F/N	L	W	Т	BW				
CL05A105KQ5NNND	1.00 ± 0.05	0.50 ± 0.05	0.50 ± 0.05	0.25 ± 0.10				

C. Samsung Reliablility Test and Judgement Condition

	Judgement	Test condition					
Capacitance	Within specified tolerance	1 ^{kHz} ±10% / 1.0±0.2Vrms					
Tan δ (DF)	0.1 max.	*A capacitor prior to measuring the capacitance is heat treated at 150° +0/-10 $^{\circ}$ for 1 hour and maintained in ambient air for 24±2 hours.					
Insulation	10,000Mohm or 100Mohm× <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding No dielectric breakdown or		250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
Characteristics	(From-55℃ to 85℃, Capacitance change s	hould be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·f, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
Solderability	More than 75% of terminal surface is to be soldered newly	with 1.0mm/sec. SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.					
Soldering Heat	Tan δ, IR : initial spec.						
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)					
Moisture Resistance	Capacitance change : within ±12.5% Tan δ : 0.125 max IR : 500Mohm or 12.5Mohm × μ ^F Whichever is smaller	With rated voltage 40±2℃, 90~95%RH, 500+12/-0hrs					
High Temperature Resistance	Capacitance change :within ±12.5%Tan δ :0.125 maxIR :1,000Mohm or 25Mohm × μFWhichever is smaller	With 100% of the rated voltage Max. operating temperature 1000+48/-0hrs					
Temperature Cycling	Capacitance change : within $\pm 7.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature → 25° C → Max. operating temperature → 25° C 5 cycle test					

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.